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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	SIO, UART/USART
Peripherals	LED, POR, Voltage Detect, WDT
Number of I/O	13
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	20-SDIP (0.300", 7.62mm)
Supplier Device Package	20-SDIP
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21194dd-v0

1.2 Performance Overview

Table 1.1 outlines the Functions and Specifications for R8C/18 Group and Table 1.2 outlines the Functions and Specifications for R8C/19 Group.

Table 1.1 Functions and Specifications for R8C/18 Group

	Item	Specification
CPU	Number of fundamental instructions	89 instructions
	Minimum instruction execution time	50 ns ($f(XIN) = 20$ MHz, $VCC = 3.0$ to 5.5 V) 100 ns ($f(XIN) = 10$ MHz, $VCC = 2.7$ to 5.5 V)
	Operation mode	Single-chip
	Address space	1 Mbyte
	Memory capacity	Refer to Table 1.3 Product Information for R8C/18 Group
Peripheral Functions	Ports	I/O ports: 13 pins (including LED drive port) Input port: 3 pins
	LED drive ports	I/O ports: 4 pins
	Timers	Timer X: 8 bits \times 1 channel, timer Z: 8 bits \times 1 channel (Each timer equipped with 8-bit prescaler) Timer C: 16 bits \times 1 channel (Input capture and output compare circuits)
	Serial interfaces	1 channel Clock synchronous serial I/O, UART 1 channel UART
	Comparator	1-bit comparator: 1 circuit, 4 channels
	Watchdog timer	15 bits \times 1 channel (with prescaler) Reset start selectable, count source protection mode
	Interrupts	Internal: 10 sources, External: 4 sources, Software: 4 sources, Priority levels: 7 levels
	Clock generation circuits	2 circuits • Main clock oscillation circuit (with on-chip feedback resistor) • On-chip oscillator (high speed, low speed) High-speed on-chip oscillator has frequency adjustment function
	Oscillation stop detection function	Main clock oscillation stop detection function
	Voltage detection circuit	On-chip
	Power-on reset circuit	On-chip
Electric Characteristics	Supply voltage	$VCC = 3.0$ to 5.5 V ($f(XIN) = 20$ MHz) $VCC = 2.7$ to 5.5 V ($f(XIN) = 10$ MHz)
	Current consumption	Typ. 9 mA ($VCC = 5.0$ V, $f(XIN) = 20$ MHz, comparator stopped) Typ. 5 mA ($VCC = 3.0$ V, $f(XIN) = 10$ MHz, comparator stopped) Typ. 35 μ A ($VCC = 3.0$ V, wait mode, peripheral clock off) Typ. 0.7 μ A ($VCC = 3.0$ V, stop mode)
Flash Memory	Programming and erasure voltage	$VCC = 2.7$ to 5.5 V
	Programming and erasure endurance	100 times
Operating Ambient Temperature		-20 to 85°C -40 to 85°C (D version)
Package		20-pin molded-plastic LSSOP
		20-pin molded-plastic SDIP
		28-pin molded-plastic HWQFN

Table 1.2 Functions and Specifications for R8C/19 Group

Item		Specification
CPU	Number of fundamental instructions	89 instructions
	Minimum instruction execution time	50 ns (f(XIN) = 20 MHz, VCC = 3.0 to 5.5 V) 100 ns (f(XIN) = 10 MHz, VCC = 2.7 to 5.5 V)
	Operation mode	Single-chip
	Address space	1 Mbyte
	Memory capacity	Refer to Table 1.4 Product Information for R8C/19 Group
Peripheral Functions	Ports	I/O ports: 13 pins (including LED drive port) Input port: 3 pins
	LED drive ports	I/O ports: 4 pins
	Timers	Timer X: 8 bits × 1 channel, timer Z: 8 bits × 1 channel (Each timer equipped with 8-bit prescaler) Timer C: 16 bits × 1 channel (Input capture and output compare circuits)
	Serial interfaces	1 channel Clock synchronous serial I/O, UART 1 channel UART
	Comparator	1-bit comparator: 1 circuit, 4 channels
	Watchdog timer	15 bits × 1 channel (with prescaler) Reset start selectable, count source protection mode
	Interrupts	Internal: 10 sources, External: 4 sources, Software: 4 sources, Priority levels: 7 levels
	Clock generation circuits	2 circuits • Main clock generation circuit (with on-chip feedback resistor) • On-chip oscillator (high speed, low speed) High-speed on-chip oscillator has frequency adjustment function
	Oscillation stop detection function	Main clock oscillation stop detection function
	Voltage detection circuit	On-chip
Power-on reset circuit	On-chip	
Electric Characteristics	Supply voltage	VCC = 3.0 to 5.5 V (f(XIN) = 20 MHz) VCC = 2.7 to 5.5 V (f(XIN) = 10 MHz)
	Current consumption	Typ. 9 mA (VCC = 5.0 V, f(XIN) = 20 MHz, comparator stopped) Typ. 5 mA (VCC = 3.0 V, f(XIN) = 10MHz, comparator stopped) Typ. 35 μA (VCC = 3.0 V, wait mode, peripheral clock off) Typ. 0.7 μA (VCC = 3.0 V, stop mode)
Flash Memory	Programming and erasure voltage	VCC = 2.7 to 5.5 V
	Programming and erasure endurance	10,000 times (data flash) 1,000 times (program ROM)
		Operating Ambient Temperature
Package		20-pin molded-plastic LSSOP 20-pin molded-plastic SDIP 28-pin molded-plastic HWQFN

1.3 Block Diagram

Figure 1.1 shows a Block Diagram.

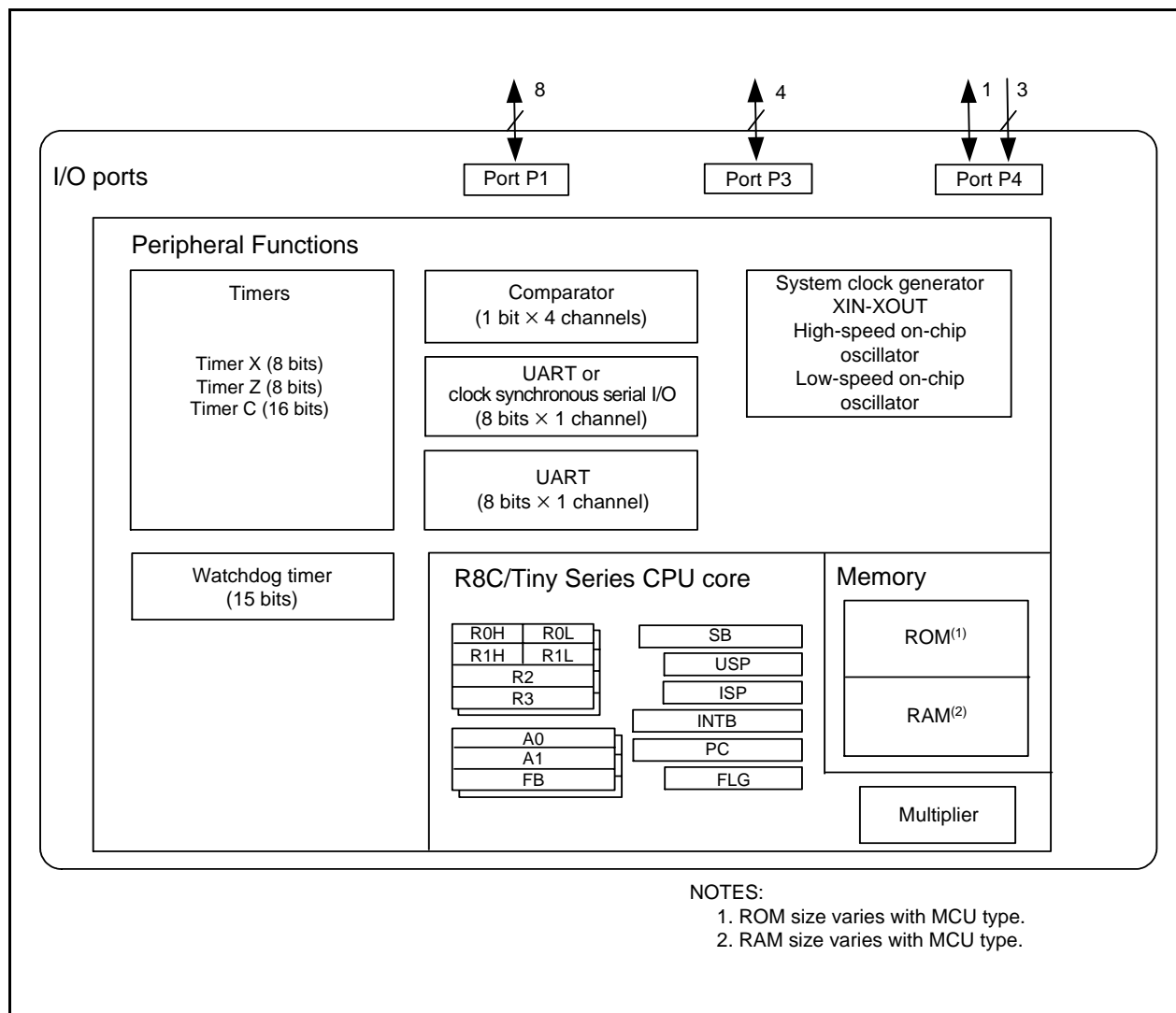
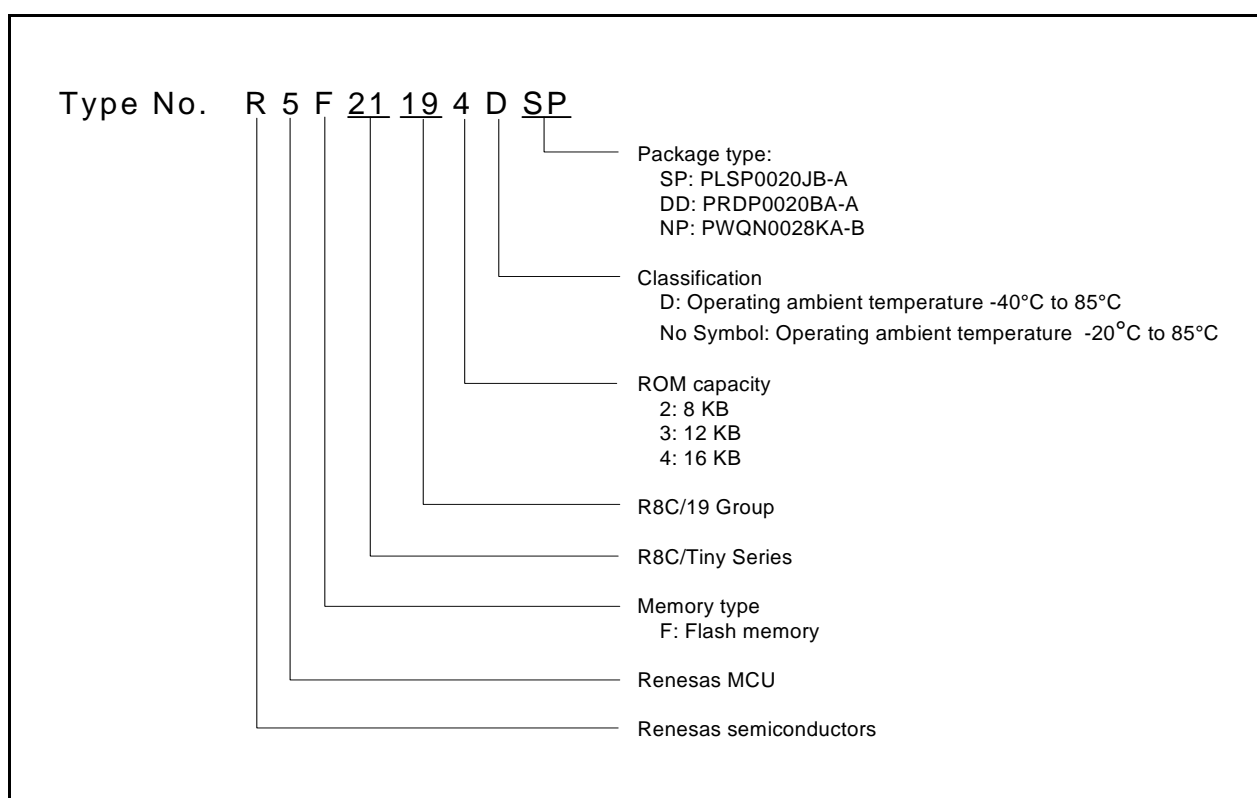


Figure 1.1 Block Diagram

Table 1.4 Product Information for R8C/19 Group**Current of Apr. 2006**

Type No.	ROM Capacity		RAM Capacity	Package Type	Remarks
	Program ROM	Data flash			
R5F21191SP	4 Kbytes	1 Kbyte × 2	384 bytes	PLSP0020JB-A	Flash memory version D version
R5F21192SP	8 Kbytes	1 Kbyte × 2	512 bytes	PLSP0020JB-A	
R5F21193SP	12 Kbytes	1 Kbyte × 2	768 bytes	PLSP0020JB-A	
R5F21194SP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLSP0020JB-A	
R5F21191DSP (D)	4 Kbytes	1 Kbyte × 2	384 bytes	PLSP0020JB-A	
R5F21192DSP (D)	8 Kbytes	1 Kbyte × 2	512 bytes	PLSP0020JB-A	
R5F21193DSP (D)	12 Kbytes	1 Kbyte × 2	768 bytes	PLSP0020JB-A	
R5F21194DSP (D)	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLSP0020JB-A	
R5F21191DD	4 Kbytes	1 Kbyte × 2	384 bytes	PRDP0020BA-A	Flash memory version
R5F21192DD	8 Kbytes	1 Kbyte × 2	512 bytes	PRDP0020BA-A	
R5F21193DD	12 Kbytes	1 Kbyte × 2	768 bytes	PRDP0020BA-A	
R5F21194DD	16 Kbytes	1 Kbyte × 2	1 Kbyte	PRDP0020BA-A	
R5F21192NP	8 Kbytes	1 Kbyte × 2	512 bytes	PWQN0028KA-B	Flash memory version
R5F21193NP	12 Kbytes	1 Kbyte × 2	768 bytes	PWQN0028KA-B	
R5F21194NP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PWQN0028KA-B	

(D): Under Development

**Figure 1.3 Type Number, Memory Size, and Package of R8C/19 Group**

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two sets of register bank.

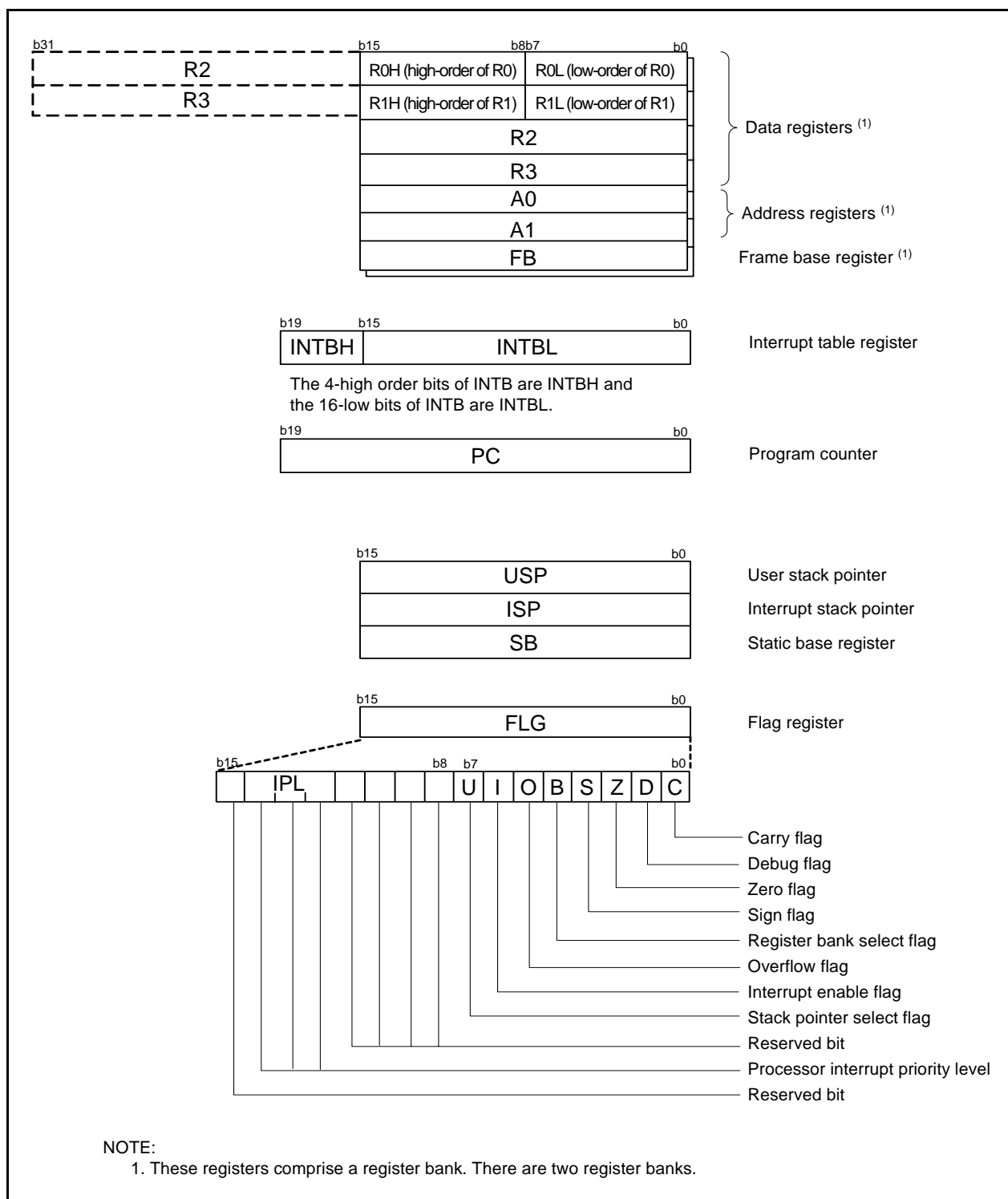


Figure 2.1 CPU Registers

2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3. R0 can be split into high-order bits (R0H) and low-order bits (R0L) to be used separately as 8-bit data registers. R1H and R1L are analogous to R0H and R0L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic and logic operations. A1 is analogous to A0. A1 can be combined with A0 and used as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the start address of an interrupt vector table.

2.5 Program Counter (PC)

PC is 20 bits wide, indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointer (SP), USP, and ISP, are each 16 bits wide. The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains a carry, borrow, or shift-out bits that have been generated by the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0; otherwise to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value; otherwise to 0.

2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is set to 1.

2.8.6 Overflow Flag (O)

The O flag is set to 1 when the operation results in an overflow; otherwise to 0.

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.

Interrupts are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.

The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide, assigns processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has higher priority than IPL, the interrupt is enabled.

2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.

4. Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 4.1 to 4.4 list the special function registers.

Table 4.1 SFR Information (1)(1)

Address	Register	Symbol	After reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	01101000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h			
0009h	Address Match Interrupt Enable Register	AIER	00h
000Ah	Protect Register	PRCR	00h
000Bh			
000Ch	Oscillation Stop Detection Register	OSD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDC	00011111b
0010h	Address Match Interrupt Register 0	RMAD0	00h
0011h			00h
0012h			X0h
0013h			
0014h	Address Match Interrupt Register 1	RMAD1	00h
0015h			00h
0016h			X0h
0017h			
0018h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h
001Dh			
001Eh	INT0 Input Filter Select Register	INT0F	00h
001Fh			
0020h	High-Speed On-Chip Oscillator Control Register 0	HRA0	00h
0021h	High-Speed On-Chip Oscillator Control Register 1	HRA1	When shipping
0022h	High-Speed On-Chip Oscillator Control Register 2	HRA2	00h
0023h			
0024h			
0025h			
0026h			
0027h			
0028h			
0029h			
002Ah			
002Bh			
002Ch			
002Dh			
002Eh			
002Fh			
0030h			
0031h	Voltage Detection Register 1 ⁽²⁾	VCA1	00001000b
0032h	Voltage Detection Register 2 ⁽²⁾	VCA2	00h ⁽³⁾ 01000000b ⁽⁴⁾
0033h			
0034h			
0035h			
0036h	Voltage Monitor 1 Circuit Control Register ⁽²⁾	VW1C	0000X000b ⁽³⁾ 0100X001b ⁽⁴⁾
0037h	Voltage Monitor 2 Circuit Control Register ⁽⁵⁾	VW2C	00h
0038h			
0039h			
003Ah			
003Bh			
003Ch			
003Dh			
003Eh			
003Fh			

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. Software reset, watchdog timer reset, and voltage monitor 2 reset do not affect this register.
3. After hardware reset.
4. After power-on reset or voltage monitor 1 reset.
5. Software reset, watchdog timer reset, and voltage monitor 2 reset do not affect b2 and b3.

Table 4.4 SFR Information (4)⁽¹⁾

Address	Register	Symbol	After reset
00C0h	A/D Register	AD	XXh
00C1h			
00C2h			
00C3h			
00C4h			
00C5h			
00C6h			
00C7h			
00C8h			
00C9h			
00CAh			
00CBh			
00CCh			
00CDh			
00CEh			
00CFh			
00D0h	A/D Control Register 2	ADCON2	00h
00D1h			
00D2h			
00D3h			
00D4h			
00D5h			
00D6h			
00D7h			
00D8h			
00D9h			
00DAh			
00DBh			
00DCh			
00DDh			
00DEh			
00DFh			
00E0h	A/D Control Register 0	ADCON0	00000XXXb
00E1h			
00E2h			
00E3h			
00E4h			
00E5h			
00E6h			
00E7h			
00E8h			
00E9h			
00EAh			
00EBh			
00ECh			
00EDh			
00EEh			
00EFh			
00F0h	A/D Control Register 1	ADCON1	00h
00F1h			
00F2h			
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh			
00FDh			
00FEh			
00FFh			
00E0h	Port P1 Register	P1	XXh
00E1h			
00E2h			
00E3h			
00E4h			
00E5h			
00E6h			
00E7h			
00E8h			
00E9h			
00EAh			
00EBh			
00ECh			
00EDh			
00EEh			
00EFh			
00F0h	Port P1 Direction Register	PD1	00h
00F1h			
00F2h			
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh			
00FDh			
00FEh			
00FFh			
00E0h	Port P3 Register	P3	XXh
00E1h			
00E2h			
00E3h			
00E4h			
00E5h			
00E6h			
00E7h			
00E8h			
00E9h			
00EAh			
00EBh			
00ECh			
00EDh			
00EEh			
00EFh			
00F0h	Port P3 Direction Register	PD3	00h
00F1h			
00F2h			
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh			
00FDh			
00FEh			
00FFh			
00E0h	Port P4 Register	P4	XXh
00E1h			
00E2h			
00E3h			
00E4h			
00E5h			
00E6h			
00E7h			
00E8h			
00E9h			
00EAh			
00EBh			
00ECh			
00EDh			
00EEh			
00EFh			
00F0h	Port P4 Direction Register	PD4	00h
00F1h			
00F2h			
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh			
00FDh			
00FEh			
00FFh			
00FCh	Pull-Up Control Register 0	PUR0	00XX0000b
00FDh		PUR1	XXXXXX0Xb
00FEh	Port P1 Drive Capacity Control Register	DRR	00h
00FFh	Timer C Output Control Register	TCOUT	00h
01B3h	Flash Memory Control Register 4	FMR4	01000000b
01B4h	Flash Memory Control Register 1	FMR1	1000000Xb
01B5h			
01B6h	Flash Memory Control Register 0	FMR0	00000001b
01B7h			
0FFFFh	Optional Function Select Register	OFS	(Note 2)

X: Undefined

NOTES:

1. The blank regions, 0100h to 01B2h and 01B8h to 02FFh are all reserved. Do not access locations in these regions.
2. The OFS register cannot be changed by a program. Use a flash programmer to write to it.

5. Electrical Characteristics

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated Value	Unit
V _{CC}	Supply voltage	V _{CC} = AV _{CC}	-0.3 to 6.5	V
AV _{CC}	Analog supply voltage	V _{CC} = AV _{CC}	-0.3 to 6.5	V
V _I	Input voltage		-0.3 to V _{CC} +0.3	V
V _O	Output voltage		-0.3 to V _{CC} +0.3	V
P _d	Power dissipation	T _{opr} = 25°C	300	mW
T _{opr}	Operating ambient temperature		-20 to 85 / -40 to 85 (D version)	°C
T _{stg}	Storage temperature		-65 to 150	°C

Table 5.2 Recommended Operating Conditions

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
V _{CC}	Supply voltage			2.7	—	5.5	V
AV _{CC}	Analog supply voltage			—	V _{CC}	—	V
V _{SS}	Supply voltage			—	0	—	V
AV _{SS}	Analog supply voltage			—	0	—	V
V _{IH}	Input "H" voltage			0.8V _{CC}	—	V _{CC}	V
V _{IL}	Input "L" voltage			0	—	0.2V _{CC}	V
I _{OH(sum)}	Peak sum output "H" current	Sum of all pins I _{OH} (peak)		—	—	-60	mA
I _{OH(peak)}	Peak output "H" current			—	—	-10	mA
I _{OH(avg)}	Average output "H" current			—	—	-5	mA
I _{OL(sum)}	Peak sum output "L" currents	Sum of all pins I _{OL} (peak)		—	—	60	mA
I _{OL(peak)}	Peak output "L" currents	Except P1_0 to P1_3		—	—	10	mA
		P1_0 to P1_3	Drive capacity HIGH	—	—	30	mA
		P1_0 to P1_3	Drive capacity LOW	—	—	10	mA
I _{OL(avg)}	Average output "L" current	Except P1_0 to P1_3		—	—	5	mA
		P1_0 to P1_3	Drive capacity HIGH	—	—	15	mA
		P1_0 to P1_3	Drive capacity LOW	—	—	5	mA
f(XIN)	Main clock input oscillation frequency		3.0 V ≤ V _{CC} ≤ 5.5 V	0	—	20	MHz
			2.7 V ≤ V _{CC} < 3.0 V	0	—	10	MHz

NOTES:

1. V_{CC} = 2.7 to 5.5 V at T_{opr} = -20 to 85 °C / -40 to 85 °C, unless otherwise specified.
2. Typical values when average output current is 100 ms.

Table 5.4 Flash Memory (Program ROM) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/erase endurance ⁽²⁾	R8C/18 Group	100 ⁽³⁾	–	–	times
		R8C/19 Group	1,000 ⁽³⁾	–	–	times
–	Byte program time		–	50	400	μs
–	Block erase time		–	0.4	9	s
t _d (SR-SUS)	Time delay from suspend request until suspend		–	–	97+CPU clock × 6 cycles	μs
–	Interval from erase start/restart until following suspend request		650	–	–	μs
–	Interval from program start/restart until following suspend request		0	–	–	ns
–	Time from suspend until program/erase restart		–	–	3+CPU clock × 4 cycles	μs
–	Program, erase voltage		2.7	–	5.5	V
–	Read voltage		2.7	–	5.5	V
–	Program, erase temperature		0	–	60	°C
–	Data hold time ⁽⁸⁾	Ambient temperature = 55 °C	20	–	–	year

NOTES:

1. V_{CC} = 2.7 to 5.5 V at T_{opr} = 0 to 60 °C, unless otherwise specified.
2. Definition of programming/erasure endurance
The programming and erasure endurance is defined on a per-block basis.
If the programming and erasure endurance is n (n = 100 or 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one. However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
4. If emergency processing is required, a suspend request can be generated independent of this characteristic. In that case the normal time delay to Suspend can be applied to the request. However, we recommend that a suspend request with an interval of less than 650 μs is only used once because, if the suspend state continues, erasure cannot operate and the incidence of erasure error rises.
5. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. In addition, averaging the number of erase operations between block A and block B can further reduce the effective number of rewrites. It is also advisable to retain data on the erase count of each block and limit the number of erase operations to a certain number.
6. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
7. Customers desiring programming/erasure failure rate information should contact their Renesas technical support representative.
8. The data hold time includes time that the power supply is off or the clock is not supplied.

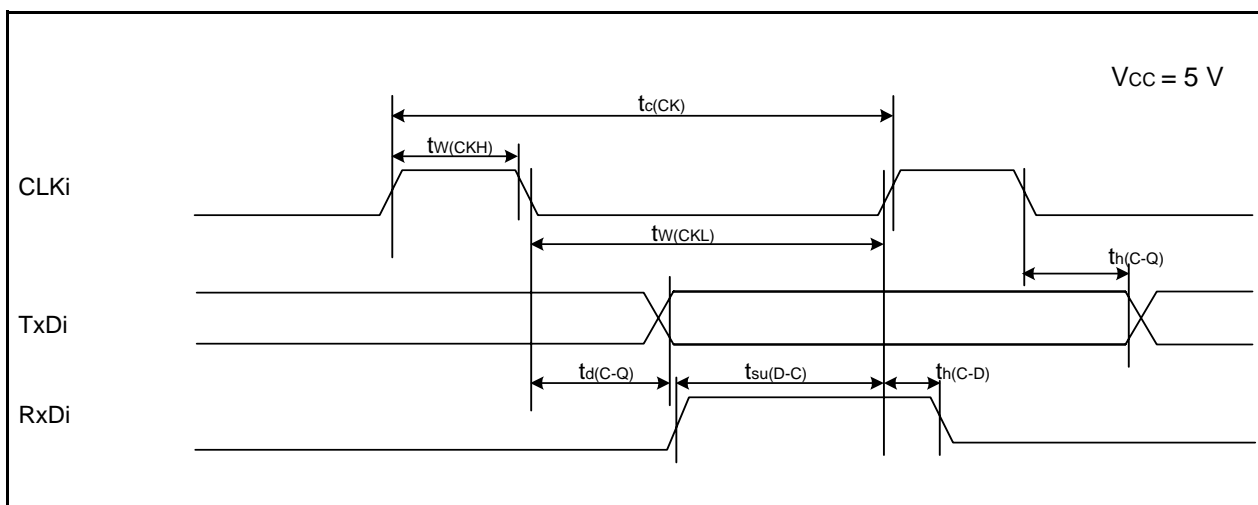
Table 5.13 Electrical Characteristics (2) [Vcc = 5 V] (Topr = -40 to 85 °C, unless otherwise specified.)

Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
Icc	Power supply current (Vcc = 3.3 to 5.5 V) Single-chip mode, output pins are open, other pins are Vss, comparator is stopped	High-speed mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	9	15	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	8	14	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	5	–	mA
		Medium- speed mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	4	–	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2	–	mA
		High-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator on = 8 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	4	8	mA
			Main clock off High-speed on-chip oscillator on = 8 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	1.5	–	mA
		Low-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8 FMR47 = 1	–	110	300	μA
		Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = 0	–	40	80	μA
		Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = 0	–	38	76	μA
		Stop mode	Main clock off, Topr = 25 °C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = 0	–	0.8	3.0	μA

Table 5.17 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	200	—	ns
$t_{w(CKH)}$	CLKi input “H” width	100	—	ns
$t_{w(CKL)}$	CLKi input “L” width	100	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	50	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	50	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

i = 0 or 1

**Figure 5.7 Serial Interface Timing Diagram when Vcc = 5 V****Table 5.18 External Interrupt $\overline{INT0}$ Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INT0}$ input “H” width	250 ⁽¹⁾	—	ns
$t_{w(INL)}$	$\overline{INT0}$ input “L” width	250 ⁽²⁾	—	ns

NOTES:

- When selecting the digital filter by the $\overline{INT0}$ input filter select bit, use an $\overline{INT0}$ input HIGH width of either (1/digital filter clock frequency x 3) or the minimum value of standard, whichever is greater.
- When selecting the digital filter by the $\overline{INT0}$ input filter select bit, use an $\overline{INT0}$ input LOW width of either (1/digital filter clock frequency x 3) or the minimum value of standard, whichever is greater.

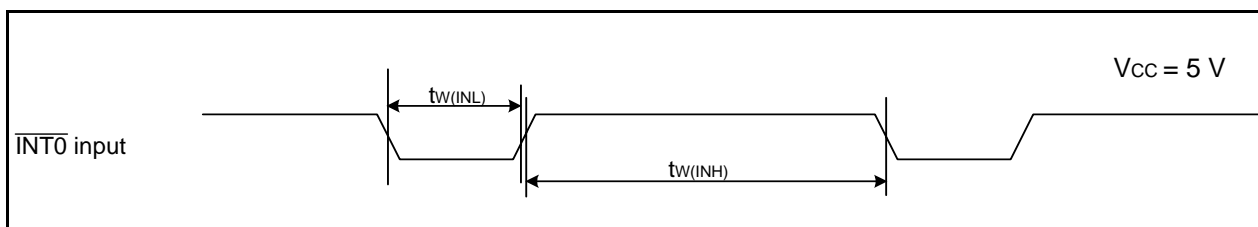
**Figure 5.8 External Interrupt $\overline{INT0}$ Input Timing Diagram when Vcc = 5 V**

Table 5.19 Electrical Characteristics (3) [V_{CC} = 3V]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Except X _{OUT}	I _{OH} = -1 mA		V _{CC} - 0.5	—	V _{CC}	V
		X _{OUT}	Drive capacity HIGH	I _{OH} = -0.1 mA	V _{CC} - 0.5	—	V _{CC}	V
			Drive capacity LOW	I _{OH} = -50 μA	V _{CC} - 0.5	—	V _{CC}	V
V _{OL}	Output "L" voltage	Except P1_0 to P1_3, X _{OUT}	I _{OL} = 1 mA		—	—	0.5	V
		P1_0 to P1_3	Drive capacity HIGH	I _{OL} = 2 mA	—	—	0.5	V
			Drive capacity LOW	I _{OL} = 1 mA	—	—	0.5	V
		X _{OUT}	Drive capacity HIGH	I _{OL} = 0.1 mA	—	—	0.5	V
			Drive capacity LOW	I _{OL} = 50 μA	—	—	0.5	V
V _{T+} -V _{T-}	Hysteresis	INT0, INT1, INT2, INT3, KI0, KI1, KI2, KI3, CNTR0, CNTR1, TCIN, RXD0			0.2	—	0.8	V
		RESET			0.2	—	1.8	V
I _{IH}	Input "H" current		V _I = 3 V		—	—	4.0	μA
I _{IL}	Input "L" current		V _I = 0 V		—	—	-4.0	μA
R _{PULLUP}	Pull-up resistance		V _I = 0 V		66	160	500	kΩ
R _{FXIN}	Feedback resistance	XIN			—	3.0	—	MΩ
f _{RING-S}	Low-speed on-chip oscillator frequency				40	125	250	kHz
V _{RAM}	RAM hold voltage		During stop mode		2.0	—	—	V

NOTE:

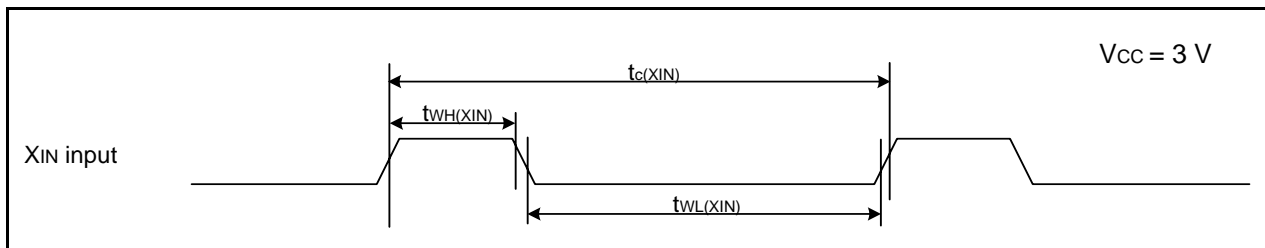
1. V_{CC} = 2.7 to 3.3 V at T_{opr} = -20 to 85 °C / -40 to 85 °C, f(XIN) = 10 MHz, unless otherwise specified.

Table 5.20 Electrical Characteristics (4) [V_{CC} = 3V] (Topr = -40 to 85 °C, unless otherwise specified.)

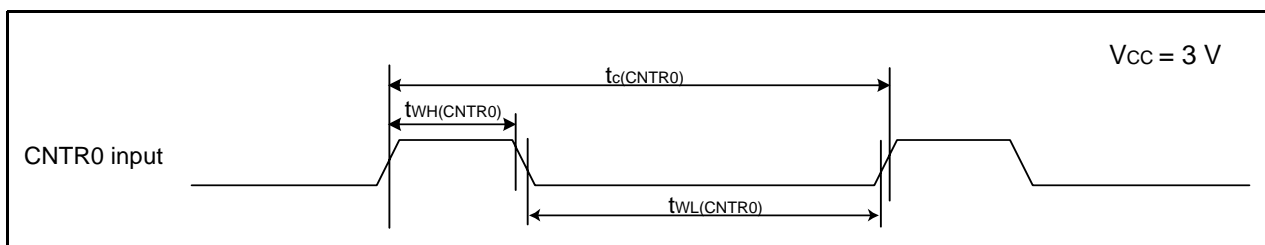
Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
I _{CC}	Power supply current (V _{CC} = 2.7 to 3.3 V) Single-chip mode, output pins are open, other pins are V _{SS} , comparator is stopped	High-speed mode	–	8	13	mA
		High-speed mode	–	7	12	mA
		High-speed mode	–	5	–	mA
		Medium- speed mode	–	3	–	mA
		Medium- speed mode	–	2.5	–	mA
		Medium- speed mode	–	1.6	–	mA
		High-speed on-chip oscillator mode	–	3.5	7.5	mA
		High-speed on-chip oscillator mode	–	1.5	–	mA
		Low-speed on-chip oscillator mode	–	100	280	μA
		Wait mode	–	37	74	μA
		Wait mode	–	35	70	μA
		Stop mode	–	0.7	3.0	μA

Timing requirements**(Unless Otherwise Specified: $V_{CC} = 3\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_a = 25\text{ }^{\circ}\text{C}$) [$V_{CC} = 3\text{ V}$]****Table 5.21 XIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	100	—	ns
$t_{WH(XIN)}$	XIN input "H" width	40	—	ns
$t_{WL(XIN)}$	XIN input "L" width	40	—	ns

**Figure 5.9 XIN Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.22 CNTR0 Input, CNTR1 Input, $\overline{INT1}$ Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CNTR0)}$	CNTR0 input cycle time	300	—	ns
$t_{WH(CNTR0)}$	CNTR0 input "H" width	120	—	ns
$t_{WL(CNTR0)}$	CNTR0 input "L" width	120	—	ns

**Figure 5.10 CNTR0 Input, CNTR1 Input, $\overline{INT1}$ Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.23 TCIN Input, $\overline{INT3}$ Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TCIN)}$	TCIN input cycle time	1,200 ⁽¹⁾	—	ns
$t_{WH(TCIN)}$	TCIN input "H" width	600 ⁽²⁾	—	ns
$t_{WL(TCIN)}$	TCIN input "L" width	600 ⁽²⁾	—	ns

NOTES:

1. When using the timer C input capture mode, adjust the cycle time to (1/timer C count source frequency × 3) or above.
2. When using the timer C input capture mode, adjust the width to (1/timer C count source frequency × 1.5) or above.

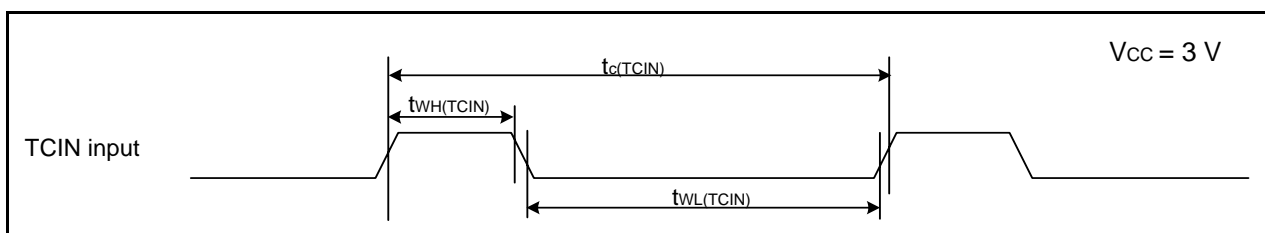
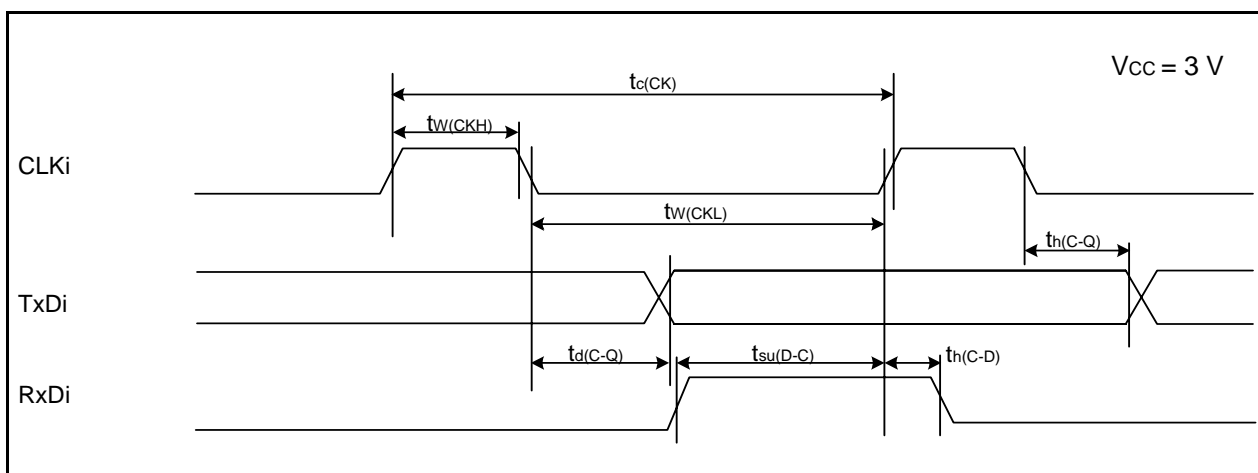
**Figure 5.11 TCIN Input, $\overline{INT3}$ Input Timing Diagram when $V_{CC} = 3\text{ V}$**

Table 5.24 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	300	—	ns
$t_{w(CKH)}$	CLKi input "H" width	150	—	ns
$t_{w(CKL)}$	CLKi input "L" width	150	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	80	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	70	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

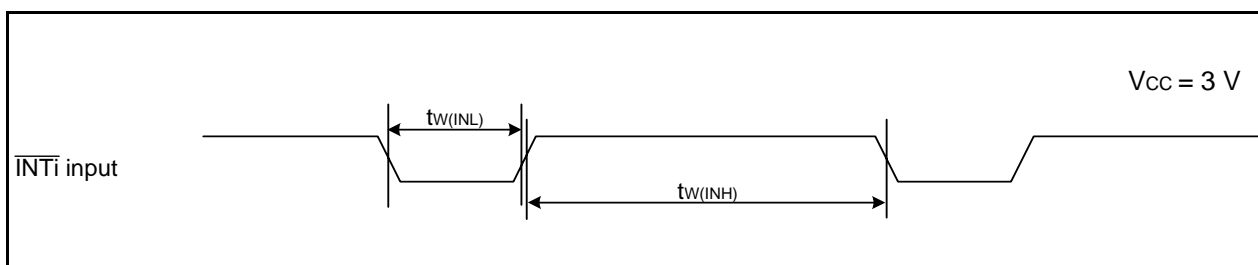
i = 0 or 1

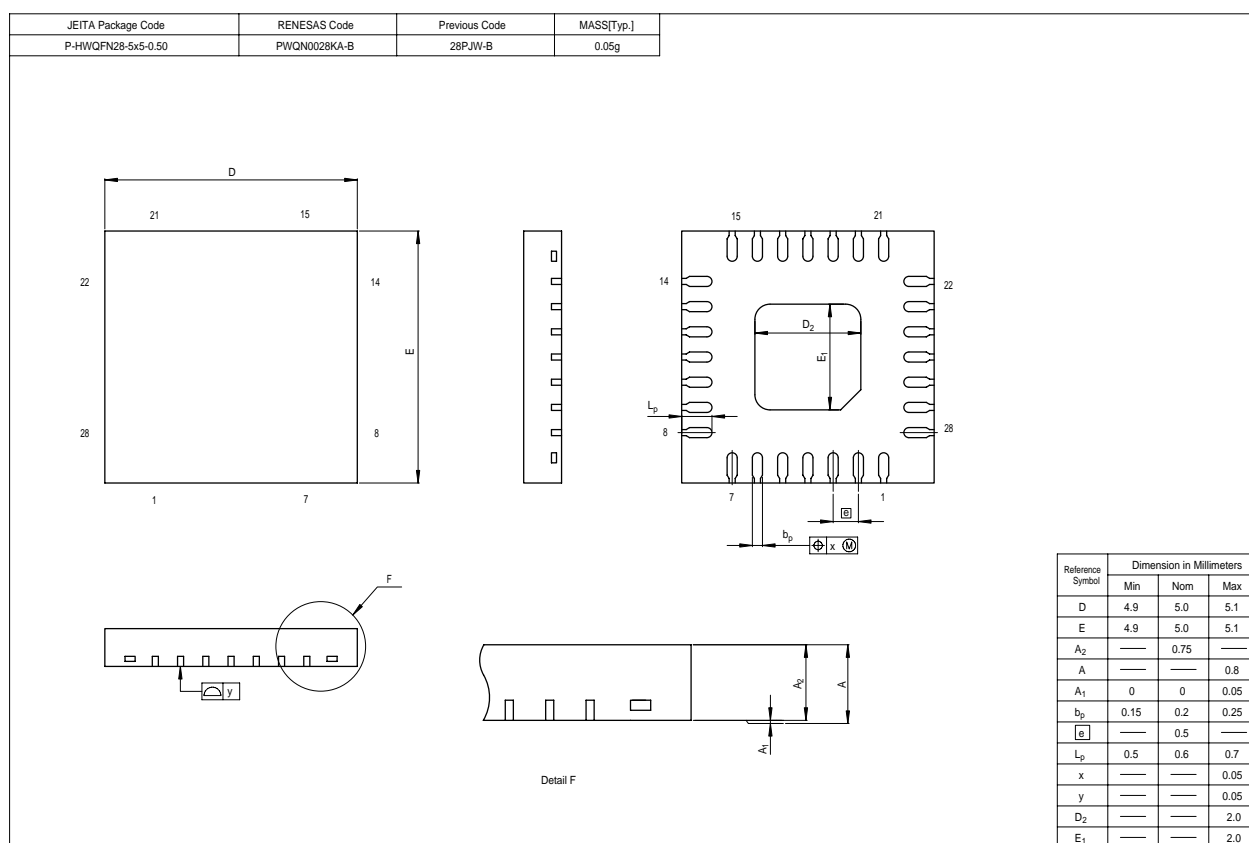
**Figure 5.12 Serial Interface Timing Diagram when Vcc = 3 V****Table 5.25 External Interrupt $\overline{INT0}$ Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INT0}$ input "H" width	380 ⁽¹⁾	—	ns
$t_{w(INL)}$	$\overline{INT0}$ input "L" width	380 ⁽²⁾	—	ns

NOTES:

1. When selecting the digital filter by the $\overline{INT0}$ input filter select bit, use an $\overline{INT0}$ input HIGH width of either (1/digital filter clock frequency x 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the $\overline{INT0}$ input filter select bit, use an $\overline{INT0}$ input LOW width of either (1/digital filter clock frequency x 3) or the minimum value of standard, whichever is greater.

**Figure 5.13 External Interrupt $\overline{INT0}$ Input Timing Diagram when Vcc = 3 V**



REVISION HISTORY		R8C/18 Group, R8C/19 Group Datasheet	
Rev.	Date	Description	
		Page	Summary
1.20	Nov 01, 2005	16	Table 4.1 SFR Information(1); 0009h: "XXXXXX00b" → "00h" 000Ah: "00XXX000b" → "00h" 001Eh: "XXXXX000b" → "00h" revised
		18	Table 4.3 SFR Information(3); 0085h: "Prescaler Z" → "Prescaler Z Register" 0086h: "Timer Z Secondary" → "Timer Z Secondary Register" 0087h: "Timer Z Primary" → "Timer Z Primary Register" 008Ch: "Prescaler X" → "Prescaler X Register" 008Dh: "Timer X" → "Timer X Register" 0090h, 0091h: "Timer C" → "Timer C Register" revised
		22	Table 5.4 Flash Memory (Program ROM) Electrical Characteristics; NOTES 3 and 5 revised, NOTE8 deleted
		23	Table 5.5 Flash Memory (Data flash Block A, Block B) Electrical Characteristics; NOTES 1 and 3 revised
		25	Table 5.8 Reset Circuit Electrical Characteristics (When Using Voltage Monitor 1 Reset); NOTE 2 revised
		26	Table 5.10 High-speed On-Chip Oscillator Circuit Electrical Characteristics; "High-Speed On-Chip Oscillator ..." → "High-Speed On-Chip Oscillator Frequency ..." revised NOTE 2, 3 added
		28	Table 5.13 Electrical Characteristics (2) [Vcc = 5V]; NOTE 1 deleted
		32	Table 5.20 Electrical Characteristics (4) [Vcc = 3V]; NOTE 1 deleted
1.30	Dec 16, 2005	–	Products of PWQN0028KA-B package included
		5, 6	Table 1.3, Table 1.4 revised
		24	Table 5.4 Flash Memory (Program ROM) Electrical Characteristics; Ta → Ambient temperature
		25	Table 5.5 Flash Memory (Data flash Block A, Block B) Electrical Characteristics; Ta → Ambient temperature
		30, 34	Table 5.13, Table 5.20; The title revised, Condition of Stop Mode added
		32, 36	Table 5.17, Table 5.24; td(C-Q) and tsu(D-C) revised
1.40	Apr 14, 2006	37, 38	Package Dimensions revised
		2, 3	Table 1.1, Table 1.2; Interrupts: Internal 8 → 10 sources,
		5, 6	Table 1.3, Table 1.4; Type No. added, deleted
		16, 17	Figure 3.1, Figure 3.2; Part Number added, deleted
		24, 25	Table 5.4, Table 5.5; Conditions: VCC = 5.0 V at Topr = 25 °C deleted

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